



High Speed Infrared Emitting Diode, 870 nm, GaAlAs Double Hetero

Description

TSFF5210 is a high speed infrared emitting diode in GaAlAs on GaAlAs double hetero (DH) technology, molded in a clear, untinted plastic package.

DH technology combines high speed with high radiant power at wavelength of 870 nm.



Features

- High modulation bandwidth (23 MHz)
- Extra high radiant power and radiant intensity
- · Low forward voltage
- Suitable for high pulse current operation
- Standard T-1¾ (Ø 5 mm) package
- Angle of half intensity $\varphi = \pm 10^{\circ}$
- Peak wavelength $\lambda_p = 870 \text{ nm}$
- · High reliability
- Good spectral matching to Si photodetectors
- Lead (Pb)-free component
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC

Applications

- Infrared video data transmission between Camcorder and TV set.
- Free air data transmission systems with high modulation frequencies or high data transmission rate requirements.

Absolute Maximum Ratings

T_{amb} = 25 °C, unless otherwise specified

| Parameter | Test condition | Symbol | Value | Unit |
|--------------------------------------|--------------------------------|-------------------|---------------|------|
| Reverse voltage | | V _R | 5 | V |
| Forward current | | I _F | 100 | mA |
| Peak forward current | $t_p/T = 0.5, t_p = 100 \mu s$ | I _{FM} | 200 | mA |
| Surge forward current | t _p = 100 μs | I _{FSM} | 1 | Α |
| Power dissipation | | P_V | 250 | mW |
| Junction temperature | | T _j | 100 | °C |
| Operating temperature range | | T _{amb} | - 40 to + 85 | °C |
| Storage temperature range | | T _{stg} | - 40 to + 100 | °C |
| Soldering temperature | $t \le 5$ sec, 2 mm from case | T _{sd} | 260 | °C |
| Thermal resistance junction/ ambient | | R _{thJA} | 300 | K/W |

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Electrical Characteristics

 T_{amb} = 25 °C, unless otherwise specified

| Parameter | Test condition | Symbol | Min | Тур. | Max | Unit |
|-------------------------------------|---|------------------|-----|-------|-----|------|
| Forward voltage | $I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$ | V _F | | 1.5 | 1.8 | V |
| | I _F = 1 A, t _p = 100 μs | V _F | | 2.3 | 3.0 | V |
| Temp. coefficient of V _F | I _F = 100 mA | TK _{VF} | | - 2.1 | | mV/K |
| Reverse current | V _R = 5 V | I _R | | | 10 | μΑ |
| Junction capacitance | V _R = 0 V, f = 1 MHz, E = 0 | C _j | | 125 | | pF |

Optical Characteristics

 T_{amb} = 25 °C, unless otherwise specified

| Parameter | Test condition | Symbol | Min | Тур. | Max | Unit |
|----------------------------------|---|------------------|-----|--------|-----|-------|
| Radiant intensity | $I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$ | I _e | 90 | 180 | 450 | mW/sr |
| | $I_F = 1 \text{ A}, t_p = 100 \mu \text{s}$ | l _e | | 1800 | | mW/sr |
| Radiant power | $I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$ | φ _e | | 50 | | mW |
| Temp. coefficient of ϕ_e | I _F = 100 mA | TKφ _e | | - 0.35 | | %/K |
| Angle of half intensity | | φ | | ± 10 | | deg |
| Peak wavelength | I _F = 100 mA | λ_{p} | | 870 | | nm |
| Spectral bandwidth | I _F = 100 mA | Δλ | | 40 | | nm |
| Temp. coefficient of λ_p | I _F = 100 mA | TKλ _p | | 0.25 | | nm/K |
| Rise time | I _F = 100 mA | t _r | | 15 | | ns |
| Fall time | I _F = 100 mA | t _f | | 15 | | ns |
| Cut-off frequency | $I_{DC} = 70 \text{ mA}, I_{AC} = 30 \text{ mA pp}$ | f _c | | 23 | | MHz |
| Virtual source diameter | | Ø | | 3.7 | | mm |

Typical Characteristics

 $T_{amb} = 25$ °C, unless otherwise specified

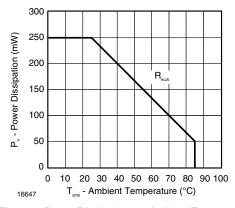


Figure 1. Power Dissipation vs. Ambient Temperature

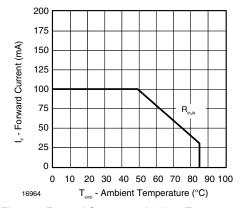


Figure 2. Forward Current vs. Ambient Temperature



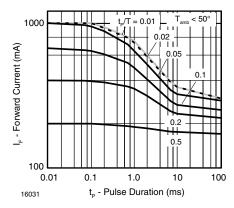


Figure 3. Pulse Forward Current vs. Pulse Duration

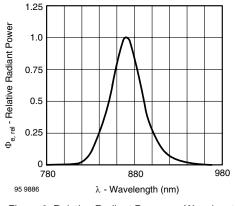


Figure 6. Relative Radiant Power vs. Wavelength

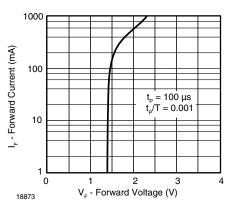


Figure 4. Forward Current vs. Forward Voltage

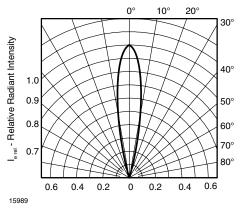


Figure 7. Relative Radiant Intensity vs. Angular Displacement

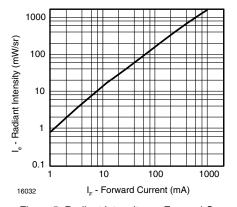


Figure 5. Radiant Intensity vs. Forward Current

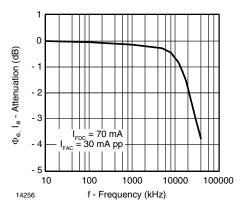
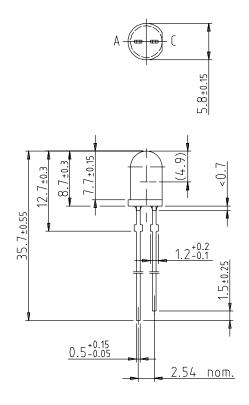
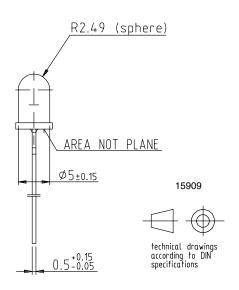


Figure 8. Attenuation vs. Frequency

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Package Dimensions in mm







Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

> We reserve the right to make changes to improve technical design and may do so without further notice.

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Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany

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